

## **IN THE CLAIMS**

Claim 1 (currently amended): A method of making an IC package mold lock comprising the steps of:

providing a first niche in a leadframe surface;

providing an opposing niche in an opposing leadframe surface, the opposing niche partially intersecting with the first niche with a step having an abrupt intersection portion such that an aperture in the leadframe is defined by the intersecting portions, and such that a key is defined by the nonintersecting portions; and

encapsulating the key with mold compound to form a mold lock.

Claim 2 (original): The method of claim 1 wherein the encapsulating step further comprises filling the first niche, opposing niche, and aperture with mold compound.

Claim 3 (original): The method of claim 1 wherein the providing steps further comprise the steps of masking and etching the leadframe surfaces.

Claim 4 (original): The method of claim 1 wherein the step of providing an opposing niche further comprises the step of providing an opposing niche axially unaligned with a first niche of approximately identical same size and shape.

Claim 5 (original): The method of claim 1 wherein the step of providing an opposing niche further comprises the step of providing an opposing niche axially aligned with a first niche of nonidentical size and shape.

Claim 6 (original): The method of claim 1 wherein the leadframe surfaces further comprise lead finger surfaces.

Claim 7 (original): The method of claim 1 wherein the leadframe surfaces further comprise die pad surfaces.